Product Change Notification

109443 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**109443 - 00**
Change Title:	**Intel(R) Hot-swap Backplane Kit AXX6DRV3GEXP, PCN 109443-00, Product Design, Add Mylar around the PCB mounting hole**
Date of Publication:	**June 29, 2009**

Key Characteristics of the Change:

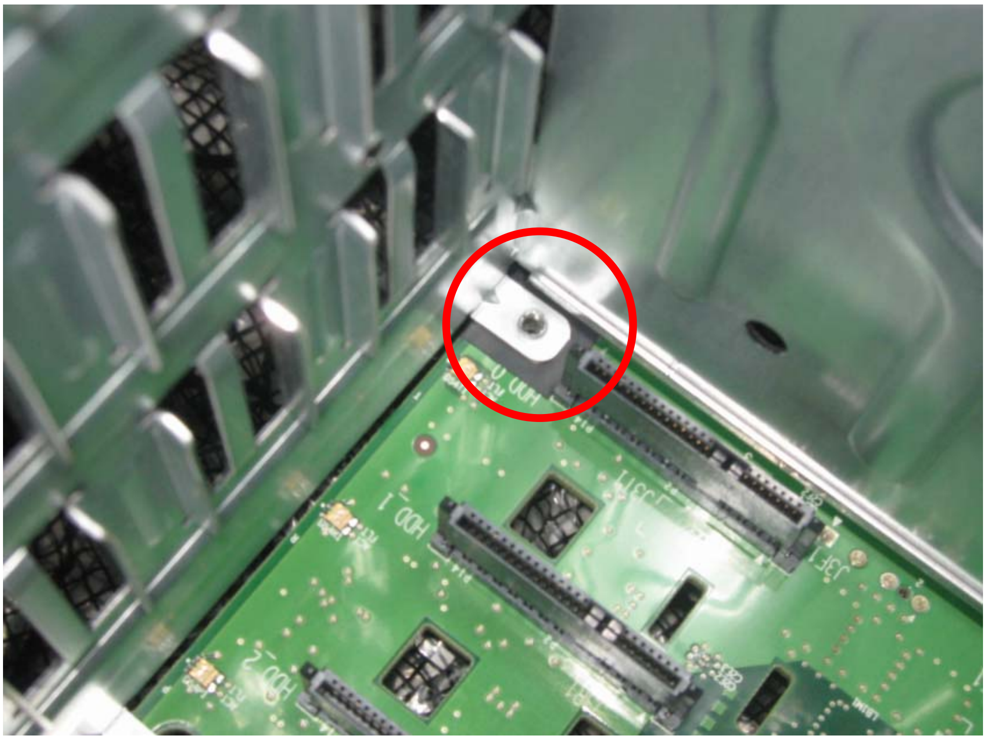
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jul 29, 2009

Description of Change to the Customer:

Intel factory will add Mylar between the backplane PCB (Printed Circuit Board) and the cage sheet metal, around the PCB mounting hole near HDD (Hard Disk Drive) slot 0 in order to increase mechanical separation and electrical insulation. Please refer to the following photo for the Mylar pad location.



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customer.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change MM#	Post Change TA
AXX6DRV3GEXP	877235	D30691-004	877235	D30691-005

Reference Documents / Attachments:

Document:	Location #:

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 29, 2009	00	Originally Published PCN